

UNIVERSAL FLIP DIE BONDER



The flip die bonder model PP5 is designed for accurate placement of delicate devices on substrate. It achieves high accuracy placement using adjustable magnification optical device.

The machine provides for single collet vacuum pick and place of die from waffle pack, Gel-Pak or bulk die media. The placement accuracy is $<5\mu\text{m}$.

A robust, and reliable mechanical concept, designed to be external vibration free.

Easy to use, flexible, the PP5 requires only minimum training to operate

SYSTEM

- PC and microcontroller
- Frame
- Vibration free

DIE & SUBSTRATE

- Minimum die size $200*200\mu\text{m}$
- Maximum die size $40*40\text{mm}$. Option more
- Substrate Up to 300 mm standard. Option more

VISION SYSTEM

- Field of view 1,2 mm.
- 2 CCD Color camera high resolution
- Digital Video Mixer
- TFT monitor 17"
- Target generator
- LED lightings & pen light
- Direct placement
- 2 references points for auto-centering placement

XY TABLE

- Motorized X 260mm, Y 120mm / $1\mu\text{m}$
- Motion control with progressive joystick weight

PARAMETERS & DISPLAY

- LCD display and TFT monitor
- Programmable force 10gr to 700gr
Opt: Heavy duty Bond Head
- Programmable bond time
- Programmable scrub
- Indexed Pick and Placement mode
- Vacuum selectable

OPTIONS

- Ultrasonic
- Dispenser
- Stamping
- UV
- Eutectic / Reflow
- Eject sytem for wafer
- Hot gaz gun or micro jet hot gas.
- Rework Station: Reflow, Epoxy, Thermoplastic

TECHNICAL SPECIFICATION

Power:	100 / 230VAC 500watt
Vacuum:	70%
Dimensions:	650*820*1450mm
Weight:	90kgr.

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